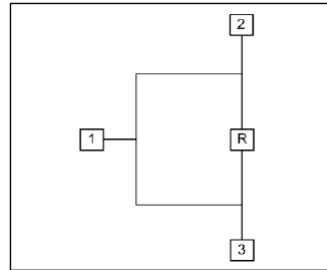


**Features**

- Frequency: 26-31GHz
- Insertion Loss: 0.3dB
- Input/Output: 50Ω matched
- Die Size: 1.25 x 1.1 x 0.1 mm

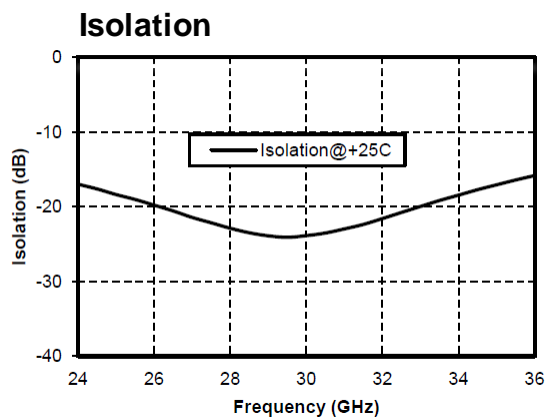
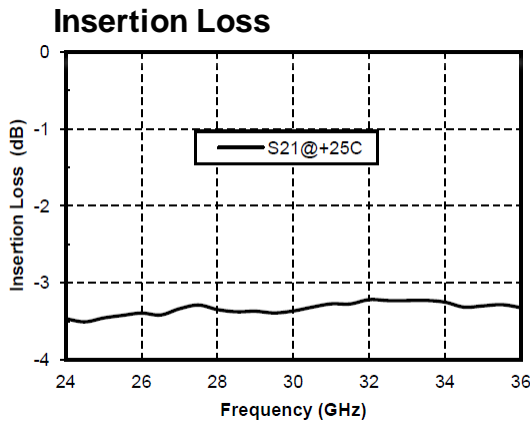
**Functional Block Diagram**



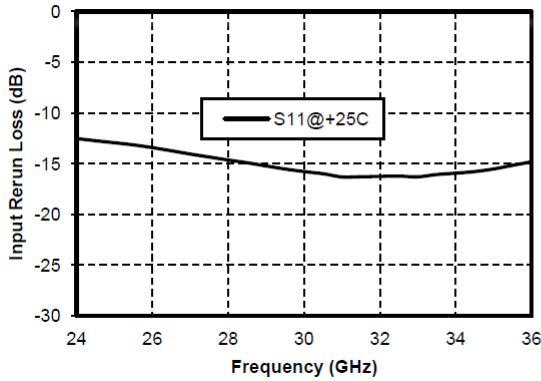
**Electrical Specifications**

TA = +25°C

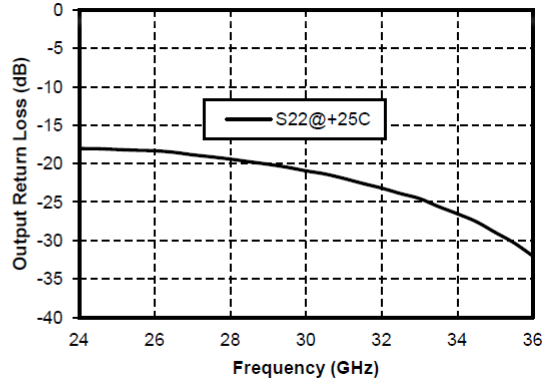
Parameters	Min.	Typ.	Max.	Units
Frequency	26-31			GHz
Insertion Loss	0.3	0.3	0.4	dB
Flatness		±0.05		dB
Isolation	20	22		dB
Input Return Loss	13	15		dB
Output Return Loss	18	20		dB



**Input Return Loss**

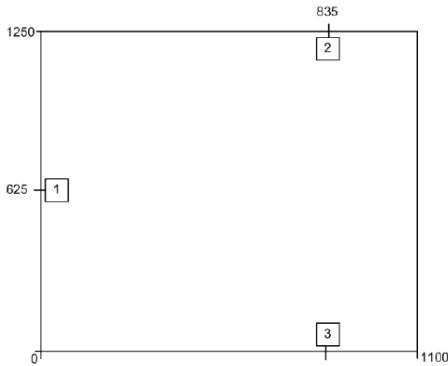


**Output Return Loss**

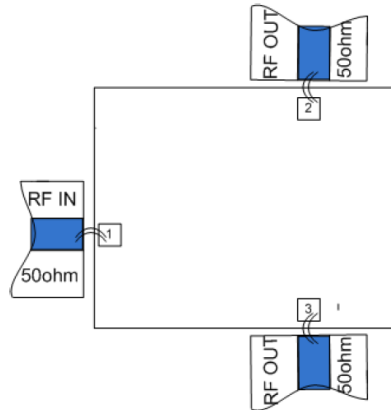


**Outline Drawing**

All Dimensions in um



**Assembly Drawing**



**Pad Description**

Pad	Function	Description
1	RF IN	RF Input Port
2,3	RF OUT	RF Output Port
Die bottom	GND	Die bottom must be connected to RF/DC ground.

**Maximum Ratings:**

1. Maximum input power: +40dBm
2. Operating temperature: -55°C to +85°C
3. Storage temperature: -65°C to +150°C